



In re the Application of

Akihiro MURATA

Application No.: 09/800,483

Filed: March 8, 2001

Docket No.: 108883

For: PLATFORM AND OPTICAL MODULE, MANUFACTURING METHOD OF THE
SAME, AND OPTICAL TRANSMISSION DEVICE

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 14, lines 14-22, delete current paragraph and insert therefor:

(27) An optical module according to the embodiments of the present invention comprises: the above described platform; an optical fiber inserted in the through hole; and an optical element electrically connected to the interconnecting line and mounted over the platform, wherein the optical element is provided within the indent so as to face an end surface of the optical fiber facing in the direction of the indent; and wherein a semiconductor chip which is electrically connected to the interconnecting line is further provided within the indent to face a surface of the optical element opposite to the surface facing the optical fiber.

Page 16, lines 18-24, delete current paragraph and insert therefor:

(34) This optical transmission device may further comprise: a plug connected to the optical element.

Page 18, lines 14-24, delete current paragraph and insert therefor:

When the mold 10 is formed of a material such as silicon or the like to which the metal of which the wire is formed does not adhere easily, a bonding pad 24 is preferably

previously formed on the mold 10. The bonding pad 24 may be a conductive film or if not electrically conductive, a film such that the wire can be attached. In this case, the wire and bonding pad 24 integrally form the interconnecting line 20. The surface of the bonding pad 24 may be formed of the same material as the wire. For example, when the wire is of gold, the bonding pad 24 may be formed of a film of chromium, with a film of gold formed thereon.

Page 19, line 20 to page 20, line 2, delete current paragraph and insert therefor:

Then, the ends of pins 32 and 34 are disposed facing the mold 10. In more detail, the pins 32 and 34 are inserted into the hole 16 formed in the mold 10. The pin 32 is fixed to the upper die 36, and when the upper die 36 and lower die 38 are closed, the pin 32 is adapted to enter the hole 16. The pin 34 functions as a pressing-out pin when the mold is opened. The pins 32 and 34 form a through hole 44 in the molding material 40 in which the optical fiber 30 is inserted. Therefore, the pins 32 and 34 are of a shape corresponding to that of the optical fiber 30.

IN THE CLAIMS:

Please cancel claims 27 and 34 without prejudice to or disclaimer of the subject matter contained therein.

Please add new claims 35 and 36 as follows:

--35. An optical module comprising: the platform as defined in claim 22; an optical fiber inserted in the through hole; and an optical element electrically connected to the interconnecting line and mounted over the platform, wherein the optical element is provided within the indent so as to face an end surface of the optical fiber facing in the direction of the indent; and wherein a semiconductor chip which is electrically connected to the interconnecting line is further provided within the indent to face a surface of the optical element opposite to the surface facing the optical fiber.--

--36 The optical transmission device as defined in claim 30, further comprising: a plug connected to the optical element.--

REMARKS

Claims 1-26, 28-33 and 35-36 are pending. By this Preliminary Amendment, the specification and claims are amended. Claims 27 and 34 are cancelled without prejudice to or disclaimer of the subject matter contained therein. Claims 35 and 36 are added. Prompt and favorable examination on the merits is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)) and claim (37 C.F.R. §1.121(c)(1)(ii)).

Respectfully submitted,



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